

REMARKS

Claims 1-9 are now pending in the application. New Claims 10-18 are presented herein for consideration. The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

Applicant was surprised to receive a rejection of the claims given the agreement reached with the Examiner that the claims distinguish over the prior art of record during the interview on March 31, 2005. Applicant is also surprised that, given the Examiner's change in position, the Examiner issued a Final Office Action. Nonetheless, while Applicant disagrees with the Examiner, Applicant has amended Claim 1 in an effort to expedite prosecution. Applicant reserves the right to pursue Claim 1 in its originally filed form in one or more continuing applications.

Applicant would also like to thank the Examiner for the courtesy extended during the telephone interview on August 15, 2005. During the interview, Applicant discussed the differences between proposed Claim 1 and the Schoenfeld reference.

REJECTION UNDER 35 U.S.C. § 102

Claims 1-4 and 6-9 stand rejected under 35 U.S.C. § 102(e) as being anticipated by Schoenfeld (U.S. Pat. No. 6,348,400). This rejection is respectfully traversed.

Schoenfeld does not show, teach or suggest providing an input/output bond pad to an outer periphery of the semiconductor die, the input/output bond pad to receive an input/output bond wire operable for electrically connecting to a lead finger of a package, wherein the lead finger is arranged on the package outside of the outer periphery of the semiconductor die.

In Schoenfeld, the lead fingers are associated with a lead frame. The portions of Schoenfeld that were identified by the Examiner do not relate to a package. Schoenfeld expressly states:

FIG. 6A depicts how multiple options pads 30 can be interconnected in such a fashion that a single wire bond or reduced number of wire bonds are made to outlying lead fingers 40 of a lead frame, which overcomes the interconnection problems described in the prior art with respect to FIG. 2. This is useful when there is an assembly limitation on the number of wire bonds that can be made to a single lead finger of a lead frame for a particular semiconductor die and lead frame design. Again, this is seen in designs that require the V_{CC} and the V_{SS} to be bonded multiple times, but the scope of the invention is not limited to those particular pins. The present invention may be used with any other bond pads of semiconductor dice that require multiple lead connections.

Schoenfeld at Col. 4, lines 41-55 (emphasis added).

The lead fingers are not located outside of an outer periphery of the semiconductor die as claimed. Rather, the lead fingers in Schoenfeld extend over an inner portion of the lead frame as shown below in FIG. 6A of Schoenfeld:

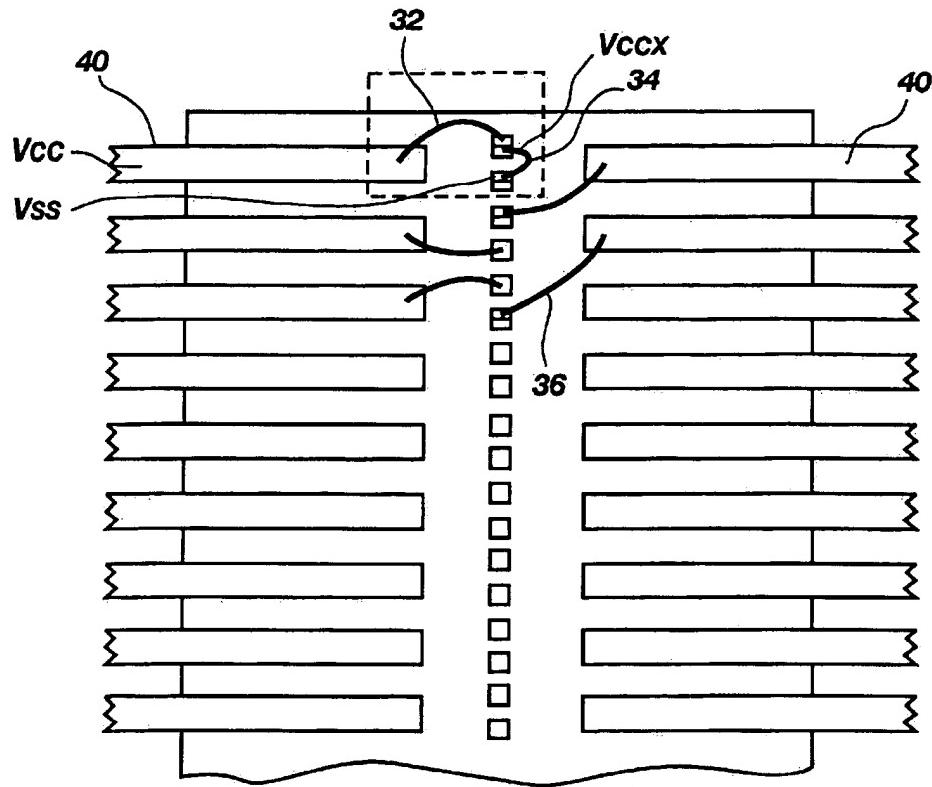


Fig. 6A

In other words, Shoenfeld teaches exactly the opposite of Claim 1 in that Shoenfeld teaches overlaying the lead fingers of a lead frame over the semiconductor die rather than arranging the lead fingers of a package outside of an outer periphery of the semiconductor die.

Claims 2-9 are directly or indirectly dependent upon Claim 1 and are therefore allowable for at least similar reasons.

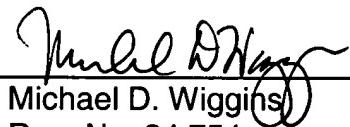
New Claim 10 is allowable for at least similar reasons as Claim 1. Claims 11-18 are directly or indirectly dependent upon Claim 10 and are therefore allowable for at least similar reasons.

CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action, and as such, the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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By: 
Michael D. Wiggins
Reg. No. 34,754

HARNESS, DICKEY & PIERCE, P.L.C.
P.O. Box 828
Bloomfield Hills, Michigan 48303
(248) 641-1600

MDW/lmt